

Certifications

Approved by ERDF

Section

MV Multifunction

ApplicationField
Laboratory**PRODUCT BENEFITS**

Tuning of the pitch of the tool

TOOL CAPACITY

Diameter	16 - 40 mm 0,630 - 1,575 inch
Non peelable semiconductor screen thickness capacity	0.4 - 1.4 mm / 0.026 - .06 inch
Insulation thickness capacity	7 mm / 0.28 inch
Chamfer angle on the non peelable semiconductor screen	14.5°

TOOL DIMENSIONS

Length	165 mm
Width	80 mm
Height	100 mm
Weight without box	1,03 Kg
Packaging	None

ALROC SAS

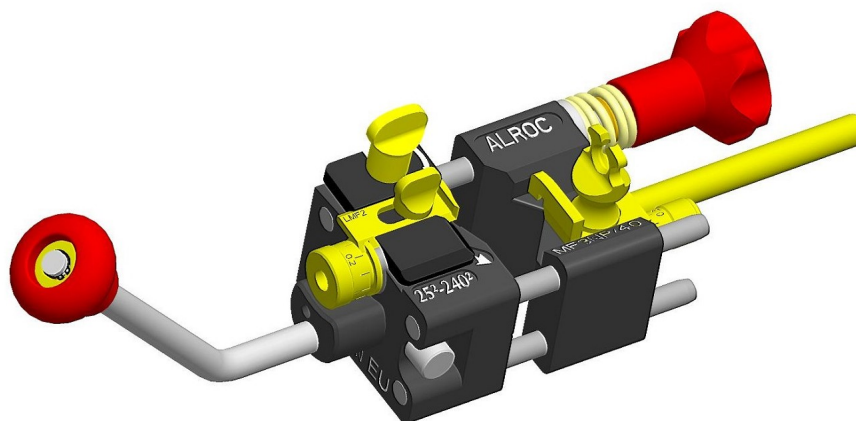
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Multifunction tool for outer sheath, bonded semiconductor and insulation

TO DO WHAT

The MF3NP/60 tools enables the user to :
Remove the outer sheath (PE-PVC-PR) with a straight and neat cut.
Remove the bonded semiconductor with a chamfer and a minimum remaining length of semiconductor of 40 mm / 1.57 inch
Remove the insulation with a neat and straight cut

Silicon required for the removal of bonded semiconductor

**Spare part**

LMF2 - Spare blade for primary insulation
PCR - Quick set up right angled 45° handle
196855 - Straight handle M10
108098 - Clamping knob for blade
LASCRI - Spare blade for bonded semiconductor
PCR - Quick set up right angled 45° handle

Associated tool

GRI-RTE - Scraper for residues of bonded semiconductor screen with protection pouch
LHA - Tool to chamfer insulation

MV cables Tools

MF3NP/40



Part Number	Diameter	Tool capacity			Dimensions			Packaging
		Non peelable semiconductor screen thickness capacity	Insulation thickness capacity	Chamfer angle on the non peelable semiconductor screen	Length	Width	Height	
MF3NP/40	16 - 40 mm 0,630 - 1,575 in	0.4 - 1.4 mm / 0.026 - .06 inch	7 mm / 0.28 inch	14.5°	165 mm 6,496 in	80 mm 3,150 in	100 mm 3,937 in	none
MF3NP/60	16 - 58 mm 0,630 - 2,283 in	0.4 - 1.4 mm / 0.026 - .06 inch	7 mm / 0.28 inch	14.5°	185 mm 7,283 in	90 mm 3,543 in	120 mm 4,724 in	none